



Orthorhombic ZrO₂ thin films via atomic layer deposition from tris(dimethylamino)cyclopentadienyl zirconium and water

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ABSTRACT

Different zirconium dioxide phases exhibit attractive functional properties, making them suitable for various applications. Among these, orthorhombic o-ZrO₂ is of particular interest due to its distinctive ferroelectric behavior. However, synthesizing phase-pure o-ZrO₂ thin films has remained challenging. Here, we demonstrate a robust water-based atomic layer deposition (ALD) process for o-ZrO₂ thin films using tris(dimethylamino)cyclopentadienyl zirconium as the precursor. The films were characterized by grazing-incidence X-ray diffraction (GIXRD), X-ray reflectivity (XRR), ellipsometry, X-ray photoelectron spectroscopy (XPS), atomic force microscopy (AFM), and photoluminescence (PL) techniques. In the deposition temperature range of 225–250 °C, the process yielded nearly phase-pure o-ZrO₂ films with a growth-per-cycle (GPC) of 0.5 Å/cycle, whereas above 275 °C, monoclinic m-ZrO₂ films were obtained with GPC of 0.6 Å/cycle. Interestingly, longer relaxation times during deposition were found to affect the growth rate, which we tentatively attributed to changes in crystallization dynamics and stabilization of different orthorhombic space groups.

1. Introduction

Zirconium dioxide is an attractive material for various emerging applications ranging from microelectronics to protective coatings in battery applications, due to its characteristic thermal, dielectric, electrical, and catalytic properties [1–3]. Under conventional synthesis conditions, ZrO₂ is obtained in multiple crystalline forms, including monoclinic (m-ZrO₂) and tetragonal (t-ZrO₂) [4,5], while the metastable orthorhombic (o-ZrO₂) phase is stabilized in powder form only under high-pressure conditions [6,7]. Due to such challenges, the unique properties of o-ZrO₂ have not been extensively studied [8,9]. Recently, the o-ZrO₂ phase has gained significant attention owing to its ferroelectric properties. Similar to o-HfO₂, the polar o-ZrO₂ phase with space group *Pca2*₁ exhibits unconventional ferroelectric behavior [10–15]. Most excitingly, the capability of o-ZrO₂ to maintain its ferroelectricity in a wider thickness range without any doping [16,17], as well as its lower crystallization temperature compared to HfO₂ [18], are highly favorable factors considering its future applications, e.g., in memory devices [19,20]. Moreover, zirconium is 50 times more Earth-abundant than hafnium.

Atomic layer deposition (ALD) is a state-of-the-art technique that enables precise control during the fabrication of high-quality thin films, making it ideal for diverse applications, particularly in electronics [21–25]. So far, various ALD processes have been developed for ZrO₂ based on different zirconium precursors (ZrCl₄, ZrI₄, Zr(thd)₄, Cp₂Zr(CH₃)₂, Cp₂ZrCl₂, Cp₂Zr(CH₃)₂, Zr[OC(CH₃)₃]₄, [Zr(C(CH₃)₃)₂(dmae)₂]₂, Zr[OC(CH₃)₃]₄) and oxygen sources (H₂O, H₂O-H₂O₂, O₃, O₂) as listed in Table 1 [26–34,39]. However, these processes have yielded either amorphous films or, in the case of crystalline films, t-ZrO₂ or m-ZrO₂ as the main phase; in the studies so far reported, the o-ZrO₂ phase has been either not seen at all or detected only as a minority phase. Developing a new ALD process capable of producing phase-pure o-ZrO₂ films would significantly advance the potential application of o-ZrO₂ as a ferroelectric component in electronic devices.

Here we present a robust water-based ALD process for ZrO₂ and evaluate its capability to produce different ZrO₂ phases, particularly the orthorhombic o-ZrO₂ phase. In this process, tris(dimethylamino)cyclopentadienyl zirconium (CpZr(NMe₂)₃) is utilized as the zirconium source; see Fig. 1 for its molecular structure. In a patent from the year

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Table 1

Reported ALD processes with complete process optimization for ZrO₂ thin films together with the resultant ZrO₂ phase composition.

Zr precursor / Co-reactant	ALD temp. window (°C): GPC (Å/c)	Substrate	Product / Temp. range	Ref.
ZrCl ₄ / H ₂ O	500: 0.53	SL glass	amor., m* or t	[26]
	280–350: 1.0	SL glass	t / 275–350,	[27]
	380–400: 5.0		m & t / 375 – 450	
ZrI ₄ / H ₂ O- H ₂ O ₂	400–600: 1.1	Si	c / 210, t & m _{TD} * / 300–600	[28]
	325–500: 0.06	Si	c & m _{TD} * / 250–375, t & m _{TD} / 300–500	[29]
Zr(thd) ₄ / O ₃	375 - 500: 0.24	Si	m & o / 300, 375	[30]
Cp ₂ Zr(CH ₃) ₂ / O ₃	310 - 500: 0.55	Si	m & o* / 300, 350	[30]
Cp ₂ ZrCl ₂ / O ₃	275 - 500: 0.53	Si	m & o* / 300, 350	[30]
Cp ₂ Zr(CH ₃) ₂ / H ₂ O	275–350: 0.43	Si	m & o* / 350–400	[31]
Zr[OC(CH ₃) ₃] ₄ / H ₂ O	150–180: 1.2 250–280: 0.07	SL glass	amorphous	[32]
[Zr(C(CH ₃) ₃) ₂ (dmae) ₂] ₂ / H ₂ O	No ALD window	SL glass	amorphous	[33]
Zr[OC(CH ₃) ₃] ₄ / O ₂ plasma	No ALD window	Si	amorphous	[34]
TDMAZr / O ₃	200 – 250: 1.25	Si	c, m & o / 150–350	[39]
CpZr(NMe ₂) ₃ / H ₂ O	200–250: 0.5	Si	o / 225–250,	This work
	275–300: 0.6		m & o* / 275–325	

* = minor phase; TD = thickness dependent.

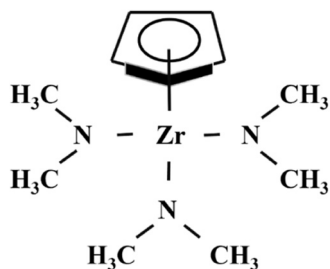
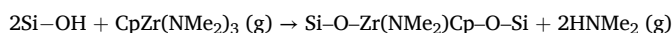


Fig. 1. Molecular structure of CpZr(NMe₂)₃ precursor.

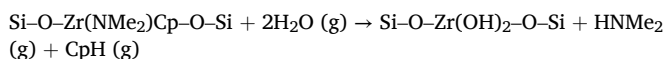
2014, CpZr(NMe₂)₃ was highlighted as a highly volatile and thermally stable precursor [35]. It was later utilized in a PEALD (plasma-enhanced ALD) process [36], as well as in an ozone-based thermal ALD process [37], both of which were conducted at high deposition temperatures, i. e., 300 and 350 °C, respectively. However, the ALD process parameters used and their optimization were not reported; likewise, the crystal structure of the resultant thin films was not thoroughly investigated at various deposition temperatures.

The possible reaction route for the CpZr(NMe₂)₃ plus water deposition process is as follows:

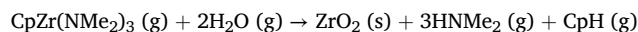
First half-cycle:



Second half-cycle:



Overall deposition reaction:



Interestingly, for HfO₂ a similar ALD process based on CpHf(NMe₂)₃ and H₂O has been employed but at much higher deposition temperatures, i.e., 305–410 °C [9]. This difference in deposition temperatures can be explained by the higher charge density of hafnium, leading to stronger metal-organic bonding and higher thermal stability.

2. Experimental

The ZrO₂ thin films were deposited from tris(dimethylamino)cyclopentadienyl zirconium (CpZr(NMe₂)₃; Dockweiler Chemicals GmbH, Germany; > 99%) and H₂O (distilled water) using a commercial ALD reactor (Picoson Oy R-100). Nitrogen (99.9%) was used as a carrier and purging gas, and the pressure was kept at 2–3 mbar in the reactor during the depositions. All the depositions were made on Si(100) wafers with a native SiO₂ layer (Okmetic Ltd.; 2 × 2 cm²) without any pretreatments. The CpZr(NMe₂)₃ precursor was heated at 110 °C for the vaporization, and the CpZr(NMe₂)₃ + H₂O process was investigated in the deposition temperature range from 200 to 325 °C. The precursor heating temperature of 110 °C was initially selected based on the information from the chemical supplier, and then adjusted by searching for the lowest heating temperature at which stable vapor pressure and reproducible mass transport were achieved; the chosen temperature is also in line with the thermogravimetric data reported for CpZr(NMe₂)₃ in literature [38]. The precursor pulse length optimization was performed at the deposition temperature of 250 °C, by varying the CpZr(NMe₂)₃ and H₂O pulse lengths between 0.4 and 1.0 s, and 0.1 and 0.4 s, respectively, while the N₂ purge length was fixed to 3 s after both precursor pulses. In addition to these conventional ALD cycles in which the total cycle time was typically 6.8 s (= 0.6 s + 3 s + 0.2 s + 3 s), we carried out a few depositions at 230, 240 and 250 °C using an “elongated-cycle” scheme to investigate the influence of extended surface relaxation times on the crystallization process; in these depositions the total cycle time was 10.8 s (= 0.6 s + 5 s + 0.2 s + 5 s) or 20.8 s (= 0.6 s + 10 s + 0.2 s + 10 s).

The film thicknesses were determined primarily by X-ray reflectivity (XRR; Rigaku SmartLab diffractometer; 45 kV and 200 mA) measurements; for some of the samples, the film thickness was additionally determined using a spectroscopic ellipsometer (Horiba UVISSEL Plus; 200 ms integration time, step size 5 nm, spot size 1 mm, incident angle 70°). The obtained data were analyzed by Horiba's DeltaPsi2 and X'Pert reflectivity software, respectively. To obtain optical constants, the ellipsometry data were freely fitted utilizing a spectroscopic model called New Amorphous [40–42]. The same X-ray diffractometer applied in XRR mode was also used for the grazing incident X-ray diffraction (GIXRD; CuKα radiation, 1.54056 Å and 1.54441 Å) mode to investigate the crystallinity and phase composition of the films; the GIXRD data were analyzed by Match 4 software. The film surface roughnesses were evaluated from the XRR data and also measured by atomic force microscopy (AFM; Bruker Dimension Icon AFM) on 2 × 2 μm² in ScanAsyst imaging mode with scan rate of 1 Hz and 512-pixels scan resolutions.

The chemical composition was investigated for three representative ZrO₂ thin films (deposited at 200, 250, and 325 °C) by X-ray photoelectron spectroscopy (XPS; Kratos Analytical AXIS Ultra, with DLD detector) using a monochromated AlKα X-ray source (1486.7 eV) run at 100 W. No sputtering was carried out on the samples, and the collection angle was 90 ° for all measurements. The XPS was operated by an Omicron Argus spectrometer at a 20 eV pass energy, and the obtained data were analyzed by the CasaXPS software package.

Photoluminescence (PL) spectra were collected using an Edinburgh Instruments FLS1000 spectrometer equipped with a continuous wave 450 W Xe arc lamp and a PMT-900 photomultiplier tube, operated at an excitation wavelength of 255 nm. A Standa BS3 filter was used on the

emission side to prevent reflected excitation from reaching to the detector.

3. Results and discussion

3.1. ALD process optimization

For the ALD process optimization, we systematically investigated the effects of the following process parameters on the ZrO_2 film growth: deposition temperature (phase composition and so-called ALD window), precursor pulse lengths (surface saturation), and number of ALD cycles applied (linearity of the film growth); the resulting changes in the film thickness were monitored with both XRR and ellipsometry measurements, to obtain the growth-per-cycle (GPC) values (= film thickness divided by ALD cycle number). The XRR results are presented in Fig. 2 and the ellipsometry results in Supporting Info, Figure S1; the trends observed are essentially parallel but it should be noted that – like here – XRR and ellipsometry may yield slightly different thickness values, explained by the fact that they probe different properties, i.e. electron density changes or optical constant differences at the film/substrate interface, respectively.

From our preliminary tests, we observed that the $\text{CpZr}(\text{NMe}_2)_3 + \text{H}_2\text{O}$ process yielded highly crystalline and nearly phase-pure o- ZrO_2

films at 250 °C; hence, the deposition temperature was fixed to 250 °C for the systematic precursor pulse length optimization experiments. The films were grown with 1000 ALD cycles in each case, and the N_2 purge time was set to 3 s for both precursors to assure – based on our previous experience on related processes – that the purge pulse is long enough to remove any excess precursor and byproduct molecules from the gas phase; note that we also confirmed for one sample that the GPC value remained unaffected when we increased the purge time from 3 s to 6 s. From Figs. 2a and 2b, the surface saturation condition is reached for the $\text{CpZr}(\text{NMe}_2)_3$ precursor with a pulse length of 0.6 s, while for the water pulse, a shorter pulse length of 0.2 s was enough for the saturation. These findings confirm the self-limiting behavior of the $\text{CpZr}(\text{NMe}_2)_3 + \text{H}_2\text{O}$ process, which is an inherent criterion of an ideal ALD process.

Subsequently, we confirmed the film growth linearity, which is another important characteristic of a well-behaving ALD process. In these experiments, the aforementioned optimized precursor and purge pulse lengths, i.e. 0.6 s / 3 s / 0.2 s / 3 s, were applied. From Fig. 2c, it is seen that the film thickness increases in an essentially linear manner when the number of cycles is increased from 200 to 2000. From the slope of the line, the average GPC value was obtained at $0.51 \pm 0.02 \text{ \AA/cycle}$. Additionally, the fact that the fitted line does not intersect the origin (zero thickness at zero cycles) but instead extrapolates to a slightly negative thickness indicates a small nucleation delay. This delay is

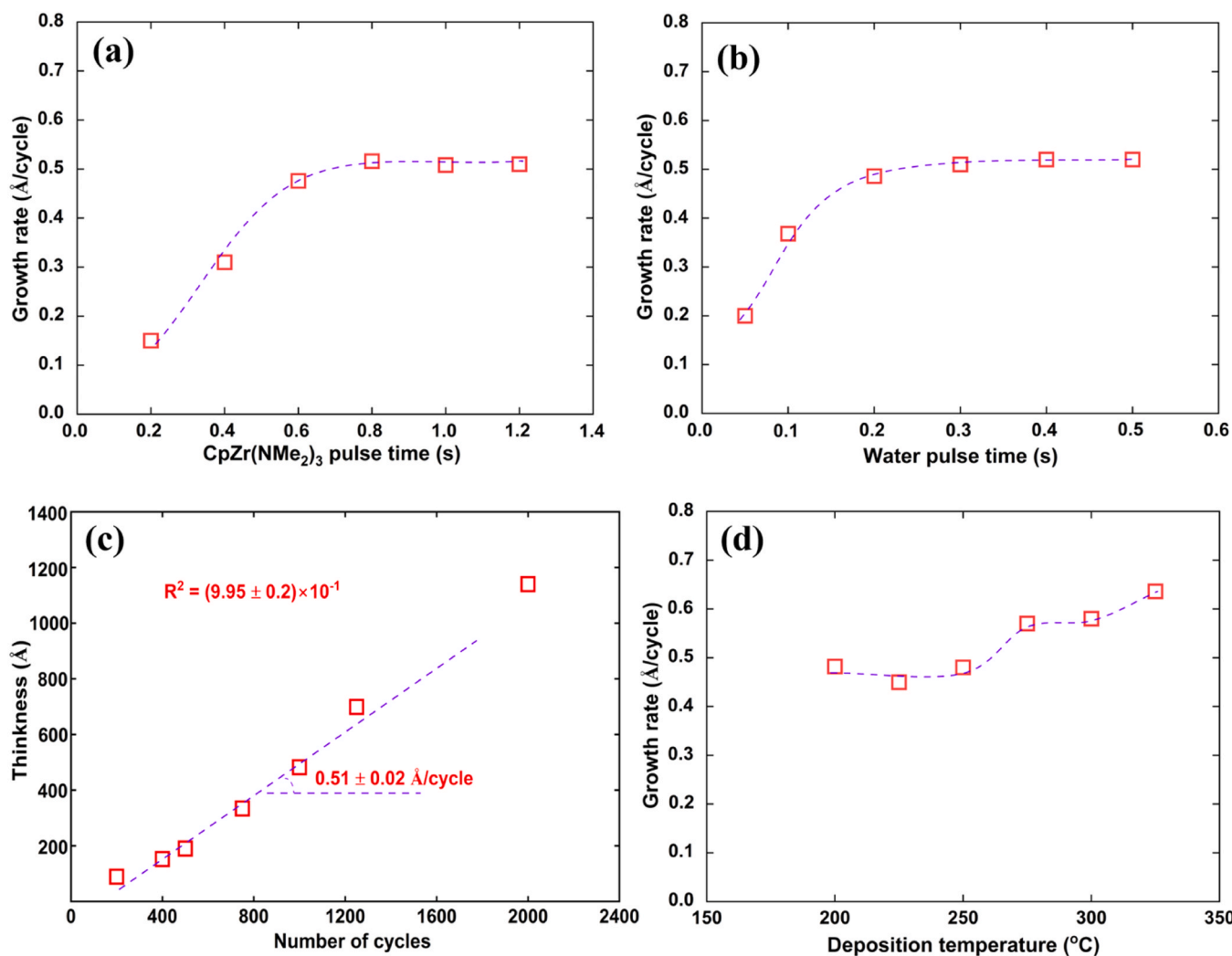


Fig. 2. ALD process optimization based on XRR data for the film thickness/GPC value: GPC versus (a) $\text{CpZr}(\text{NMe}_2)_3$ precursor, and (b) water pulse lengths; (c) film thickness versus number of ALD cycles; (d) GPC versus deposition temperature. In all these experiments the fixed parameters were (when one of the parameters was varied): deposition temperature 250 °C, number of ALD cycles 1000, and pulse/purge sequence 0.6 s / 3 s / 0.2 s / 3 s.

minor though, as the film has already reached ca. 9 nm thickness by 200 cycles.

Finally, we investigated the film growth at different deposition temperatures in the 200–325 °C range, as shown in Fig. 2d. In preliminary experiments, we found that some deposition occurred even at 180 °C, but the resulting films were non-uniform and were therefore excluded from further investigations. The upper temperature limit of 325 °C was defined by our reactor limitations. From Fig. 2d, two distinct GPC plateaus (or ALD windows) are seen, around 200–250 °C (GPC ca. 0.5 Å/cycle) and 275–325 °C (GPC ca. 0.6 Å/cycle). These observed differences in the GPC value within the two plateaus likely originate from the different crystal structures of the ZrO₂ product, as discussed in detail in the subsequent section.

3.2. Film characterization

To investigate the phase composition of the films deposited at different temperatures ranging from 200 to 325 °C, GIXRD patterns were acquired, as presented in Fig. 3. So far in literature, the most common experimentally verified crystal structures for ZrO₂ are as follows: monoclinic (P2₁/c: JCPD 96–152–8985), orthorhombic (Pbca, Pca2₁ & Pnma: JCPD 04–007–0952, 96–900–9920, 00–049–1746), tetragonal (P4₂/nmc: JCPD 96–152–5706), and cubic (Fm3̄m: JCPD 96–152–1754). Note that for the orthorhombic phase, several alternative space groups have been reported, but it is truly challenging if not impossible to distinguish between these different space groups based on standard diffraction techniques. In addition to GIXRD, other research groups have also utilized Raman spectroscopy for phase determination [37]; however, our efforts were not successful.

The film deposited at 200 °C was predominantly amorphous, the GIXRD pattern showing only a few weak diffraction peaks. With increasing deposition temperature, the degree of crystallinity systematically increased, such that up to 250 °C the diffraction peaks and their positions remained the same; essentially all the diffraction peaks seen for these films could be indexed according to the orthorhombic (Pca2₁) o-ZrO₂ structure, except the weak peak around 28.4° which could be the main diffraction peak due to m-ZrO₂. Then, upon a further increase in the deposition temperature the crystal structure clearly changed to the monoclinic m-ZrO₂ (P2₁/c) structure. The volume per formula unit (V_{f.u.}) for the monoclinic m-ZrO₂ structure is larger (35.4 Å³/f.u.) compared to the orthorhombic o-ZrO₂ structure (34.2 Å³/f.u. for Pca2₁, 33.9 Å³/f.u. for Pbca, 31.4 Å³/f.u. for Pnma); interestingly, this is well in line with the higher GPC values observed for the m-ZrO₂ films (higher deposition temperature range in Fig. 2d). We also like to note that the peak

positions observed for the two phases are in line with those previously reported in literature [43,44]: 24.08° (m-ZrO₂), 24.44° (o-ZrO₂), 28.39° (m-ZrO₂), 30.36° (o-ZrO₂), 31.55° (m-ZrO₂), 34.6° (m-ZrO₂), 35.48° (o-ZrO₂), 38.9° (m-ZrO₂), 41.2° (m-ZrO₂), 45.05° (m-ZrO₂), 59.96° (m-ZrO₂), 60.61° (o-ZrO₂), 62.81° (m-ZrO₂), 63.25° (o-ZrO₂), and 66.03° (m-ZrO₂). Finally, we confirmed for the 250 °C deposited samples the o-ZrO₂ phase stability in relation to the film thickness; the GIXRD patterns shown in Figure S2 (Supporting info) reveal no visible thickness-dependent differences.

During the process development stage, the films were deposited already with a relatively long overall ALD cycle duration of 6.8 s (0.6 s + 3 s + 0.2 s + 3 s) for which the pulse and purge durations were considered sufficient to supply the precursors and remove the process residuals. However, we wanted to investigate the influence of significantly elongated deposition cycles on the crystallization of the films through relaxation time enhancement. For this, we carried out additional depositions at 240 and 250 °C (i.e., at the two deposition temperatures yielding the most crystalline orthorhombic phases) and increased the total cycle time by threefold from 6.8 to 20.8 s (= 0.6 s + 10 s + 0.2 s + 10 s). As anticipated, the longer cycle time resulted in a higher degree of crystallinity, see Fig. 4. However, in the sample deposited at 250 °C, it also resulted in a partial phase change from orthorhombic to monoclinic, while the sample deposited at 240 °C was highly crystalline and showed only traces of the m-ZrO₂ phase. Most interestingly, the GPC value seemed to be significantly lower (ca. 0.35 Å/cycle) for this 240 °C sample compared to the values obtained for the films deposited with the “optimized” shorter cycle time (ca. 0.5 Å/cycle) in the “orthorhombic” deposition temperature range of 225 – 250 °C. Because of the higher degree of crystallinity, the films deposited with the elongated cycle time were exceptionally rough, and therefore their thicknesses were challenging to determine with XRR. To corroborate the result, we carried out additional depositions at 230 and 240 °C using an intermediate overall cycle duration of 10.8 s (= 0.6 s + 5 s + 0.2 s + 5 s); the GPC values determined by ellipsometry measurements were 0.37 and 0.36 Å/cycle, respectively. The lower growth rate values could be explained as a consequence of the previously reported effect of longer purge duration on the growth rate due to desorption of attached precursors on the surface [45], or due to the higher degree of crystallinity and thus a somewhat higher density of the growing o-ZrO₂ film. Finally, a third plausible reason or contributing factor could be stabilization of a slightly different crystal structure with a lower V_{f.u.}, i.e. o-ZrO₂ structure with space group Pbca (33.9 Å³/f.u.) or Pnma (31.4 Å³/f.u.), instead of Pca2₁ (34.2 Å³/f.u.) [6,46,47]. However, all these suggested explanations remain tentative and require validation

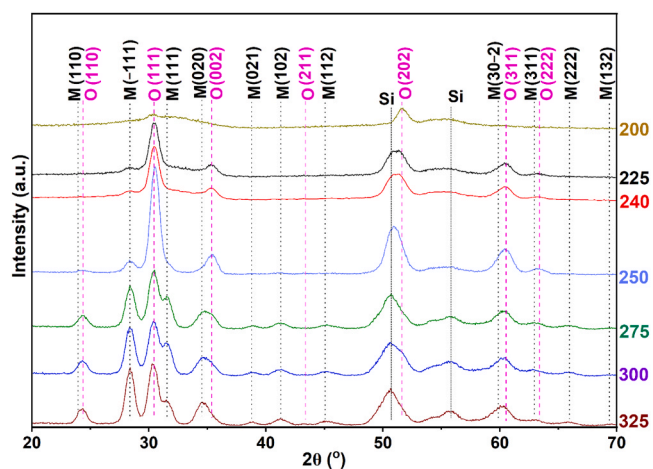


Fig. 3. GIXRD patterns for ZrO₂ films deposited at various temperatures, using the following deposition parameters: number of ALD cycles 1000, and pulse/purge sequence 0.6 s / 3 s / 0.2 s / 3 s; Si stands for silicon substrate.

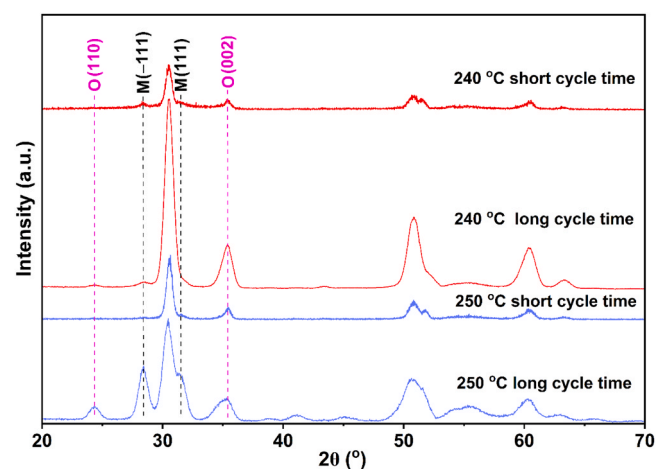


Fig. 4. GIXRD patterns for the ZrO₂ thin films deposited at 240 and 250 °C with the shorter (6.8 s) and longer (20.8 s) cycle durations; the number of ALD cycles applied was 1000.

through complementary analytical methods.

The XRR patterns for the ZrO₂ films deposited (with the optimized/shorter cycle duration) at temperatures from 200 to 325 °C are shown in Fig. 5. From the critical angles obtained from the XRR patterns [48], the film densities were calculated at ca. 4.6 g/cm³ for these films (ideal bulk density of ZrO₂: 5.68 g/cm³). It should be emphasized that the difference seen here between the thin-film and ideal-bulk density values is rather typical for high-quality pinhole-free ALD thin films [43], e.g. for HfO₂ films 7.7 g/cm³ versus 9.6 g/cm³ [49]. Most of the samples exhibited very similar XRR patterns except the two grown at 240 and 250 °C, which appeared significantly rougher compared to the others (oscillations weaker in magnitude). Similarly, AFM measurements yielded higher roughness values for these two thin films, ca. 4.1 nm in comparison to the ca. 2.5 nm for the other samples (Fig. 6, Table 2). Tentatively, we attribute the anomalous roughness values of the 240 and 250 °C samples to their small but emerging two-phase character, even though the m-ZrO₂ phase is below the detection limit of GIXRD in the 240 °C sample. The AFM images, moreover, revealed that the coatings were appreciably uniform and pinhole-free, like also expected based on other characterizations and visual observations.

To gain further understanding of the film composition, XPS spectra were collected for representative samples; the XPS core-level spectra of films grown at 200, 250, and 325 °C (Fig. 7) indicate a single ZrO₂ lattice doublet of Zr 3d with 3d_{5/2} = 182.0 ± 0.1 eV, 2.39 eV spin-orbit splitting, almost equal FWHM, and a 3d_{5/2}/3d_{3/2} area ratio of 3:2, which are consistent with fully oxidized Zr⁴⁺. No other phases, such as suboxides, were detected. In the O 1s region, the lattice O²⁻ appears at 529.9 ± 0.2 eV, while the -OH/oxygen defect peak is seen at 531.3–531.7 eV [50–52]. The -OH fraction systematically decreases with increasing deposition temperature, from 32% at 200 °C to 18% at 250 °C, and 17% at 325 °C, indicating increasing dehydroxylation. The C 1s region is dominated by adventitious C-C/C-H with a minor O-C-/C=O feature at 288.5–288.7 eV and 7–10% fraction, the latter being attributed to surface carboxylate/carbonate-like species formed upon ambient exposure of the hydroxylated oxide surface [53,54]. Overall, the spectra confirm the expected ZrO₂ phase across the sample series with no other Zr

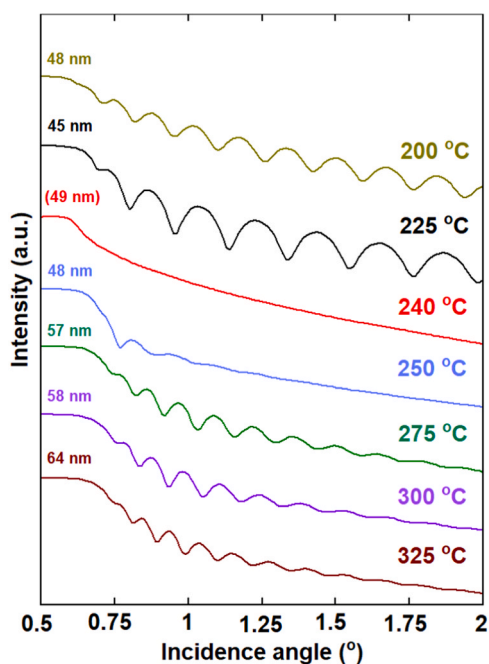


Fig. 5. XRR patterns for the ZrO₂ thin films deposited at various temperatures. The film thickness is indicated on the left; for the 240 °C sample, the thickness value is in parentheses as it was determined by ellipsometry. All other parameters except the deposition temperatures were the same for all samples.

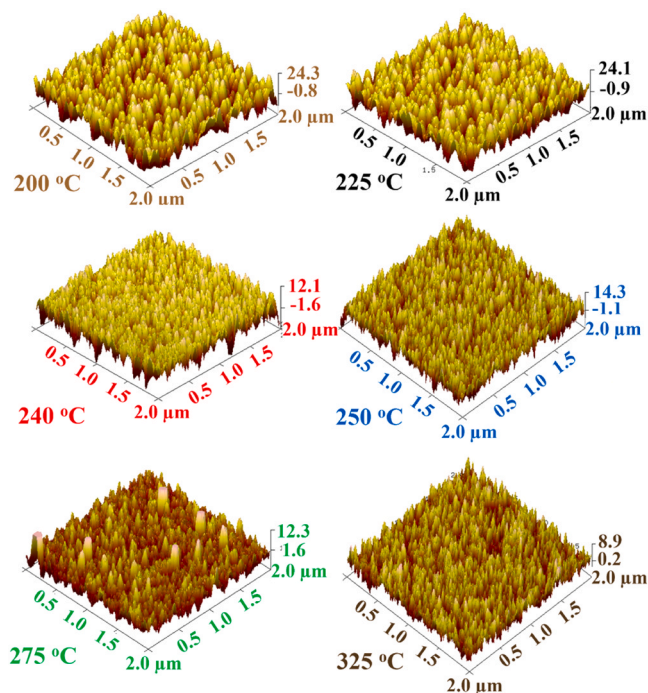


Fig. 6. 3D AFM images for the ZrO₂ thin films deposited at 200, 225, 240, 250, 275, and 325 °C with the short cycle duration scheme and 1000 ALD cycles.

Table 2

Surface roughness of the ZrO₂ thin films deposited at different temperatures with the normal cycle time; the film thicknesses are seen from Fig. 5.

Dep. Temp. (°C) (Dominant phase)	RMS roughness (nm)
200 (o)	2.3
225 (o)	2.4
240 (o)	3.9
250 (o, m*)	4.3
275 (m, o*)	2.8
325 (m, o*)	2.6

* = minor phase

formations or significant contaminations (see also the full XPS survey spectra in SI, Figure S3), with reduced surface hydroxylation at higher processing temperatures.

Photoluminescence spectroscopy is widely used to characterize defect states in oxide thin films. In this study, PL measurements were performed on two samples deposited at 240 and 325 °C (Fig. 8). The sample deposited at 240 °C exhibits peaks in the near-UV (350–400 nm) and blue-band (440–470 nm) ranges. The near-UV region is commonly assigned to oxygen-related defects, specifically deep oxygen vacancies (Vo₂) [55–60], while the luminescence in the blue-band range has been attributed to both surface hydroxyl groups and oxygen-related defects (e.g., F-centers) [55,60–65]. Similar features are also observed in the sample deposited at 325 °C. For this reason and given the similar high binding energy oxygen ratios in XPS for 250 and 325 °C samples, we consider it more likely that, in this case, the blue-band emission originates from surface hydroxyl groups. The 325 °C sample, however, lacks the 350–400 nm transitions, while it exhibits a long yellow-green tail after the blue-band peak, extending up to 625 nm. This feature has been associated with both impurities (e.g., Ti and Hf) and shallow oxygen defects (Vo₁) [57,58,65–67]. However, since such impurities are not present, the emission is attributed to shallow oxygen defects. Therefore, the sample deposited at 325 °C, exhibiting both the blue band and the yellow-green tail, is inferred to contain surface hydroxyl groups along with shallow oxygen defects, whereas the 240 °C sample contains

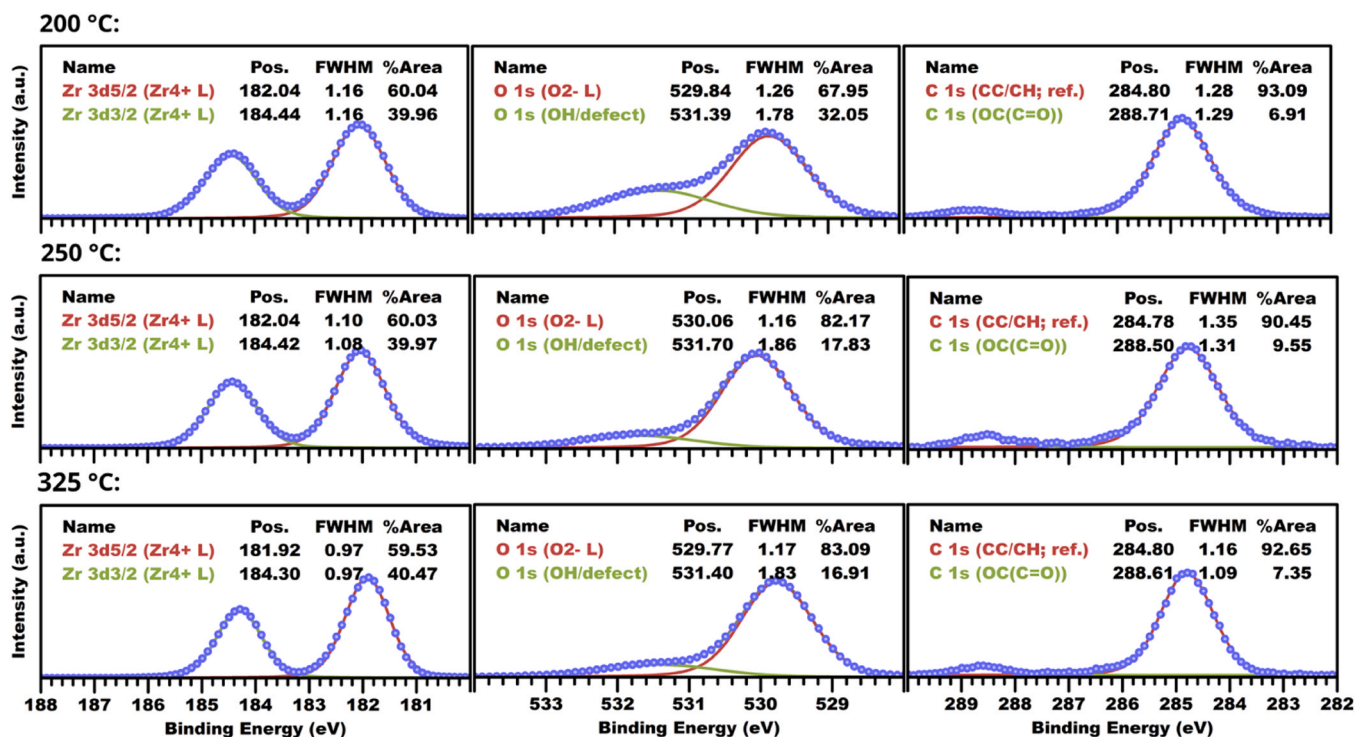


Fig. 7. XPS core-level spectra (left column: Zr 3d, middle: O 1 s, right: C 1 s) for three representative ZrO₂ thin-film samples deposited at 200, 250 and 325 °C, with experimental and fitted data plotted as dotted and solid lines, respectively; the binding energy scale was calibrated using C 1 s at 284.80 eV as a reference.

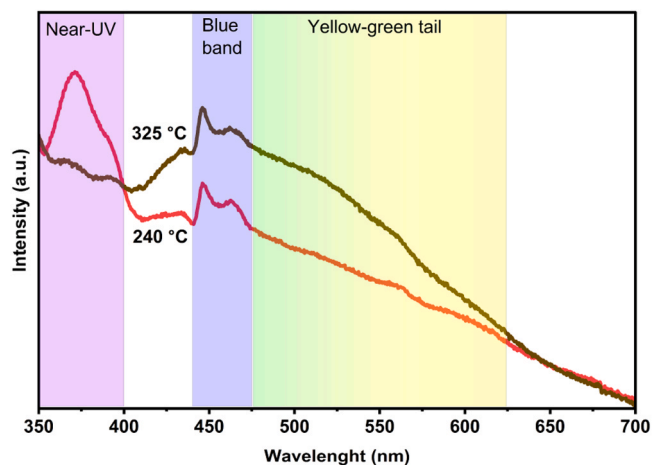


Fig. 8. Photoluminescence spectra of ZrO₂ films deposited at 240 and 325 °C.

surface hydroxyls along with deep oxygen defects. Considering that ZrO₂ can accommodate oxygen defects in both the monoclinic and orthorhombic forms, these findings do not provide definitive evidence regarding the phase type. However, they do indicate that different phases may favor different defect types. Specifically, the orthorhombic phase (sample deposited at 240 °C) appears to favor deep oxygen defects, whereas the monoclinic phase (sample deposited at 325 °C) appears to favor shallow oxygen defects.

3.3. Factors promoting the o-ZrO₂ formation

From previous studies on the polar o-ZrO₂ phase synthesized by various techniques [68–73], the most important factors promoting the formation of this metastable phase seem to be the low synthesis temperature and the existence of oxygen defects (vacancies). Apparently,

our ALD CpZr(NMe₂)₃/H₂O process, yielding nearly phase-pure o-ZrO₂ thin films in the deposition temperature range of 225–250 °C, simultaneously satisfies these factors. Indeed, compared to the other reported ALD processes for crystalline ZrO₂ thin films (not yielding the orthorhombic phase), the present deposition temperature range (225–250 °C) is appreciably low, see Table 1. Also, our process utilizes H₂O as the co-reactant, which is a significantly milder oxidant than the other commonly utilized co-reactants, O₃ and O₂-plasma, and hence more likely to create oxygen vacancies that are believed to have a stabilizing effect on the o-ZrO₂ structure. Finally, the Si/SiO₂ substrate used here could promote the o-ZrO₂ phase formation; a similar facilitating effect of substrate surface on the o-ZrO₂ phase formation was also observed with a Ru sublayer [36]. From Table 1, all the earlier ALD processes reported have missed at least one of the aforementioned factors.

4. Conclusions

We demonstrated a robust water-based ALD process for the fabrication of orthorhombic o-ZrO₂ thin films, using tris(dimethylamino) cyclopentadienyl zirconium as the Zr precursor. The process could be readily optimized regarding the precursor pulse lengths to demonstrate the surface-saturation and growth-linearity behaviors expected for an ideal ALD process. The optimized ALD process with appreciably short precursor pulse lengths (0.6 s for CpZr(NMe₂)₃ and 0.2 s for H₂O) revealed a so-called ALD or constant-GPC (ca. 0.5 Å/cycle) temperature window of 200–250 °C for the growth of the o-ZrO₂ films, while in the higher deposition temperature range of 275–325 °C the process yielded monoclinic m-ZrO₂ films with a growth rate of 0.6 Å/cycle.

The o-ZrO₂ and m-ZrO₂ thin films distinguishably obtained in the lower and higher deposition temperature ranges, respectively, exhibited – besides the different growth rates and GIXRD patterns – somewhat different XPS and PL spectra presumably due to different oxygen defect types. In particular, the differences seen in the photoluminescence spectra for the ZrO₂ films grown at the lower and higher temperatures reflected the general understanding that the o-ZrO₂ and m-ZrO₂ phases tend to accommodate different types of oxygen defects.

We tentatively attribute our success to fabricate through the CpZr (NMe₂)₃/water process nearly phase-pure thin films of the metastable o-ZrO₂ phase to the significantly low deposition temperature range (225–250 °C) and mild oxygen source (H₂O). These deposition conditions apparently promote the formation of the proper types of oxygen defects (vacancies) that are believed to stabilize the o-ZrO₂ structure.

The GIXRD patterns obtained for all the o-ZrO₂ thin films deposited in the range of 225–250 °C were fully compatible with the space group Pca2₁ reported for ferroelectric polar o-ZrO₂. However, with the standard in-house characterization techniques employed in this study it was not possible to rule out the other two space groups (Pbca and Pnma) also reported for o-ZrO₂ in literature. Interestingly, from the deposition experiments in which we increased the ALD cycle time considerably (at deposition temperatures of 230 and 240 °C) we noticed that while the GIXRD patterns were still compatible with the o-ZrO₂ structure (though with a lower degree of crystallinity), the GPC values were lower. Tentatively, we hypothesize that one of the plausible interpretations could be that the shorter ALD cycle time favors the formation of the Pca2₁ space group (with larger V_{f.u} and lower density), while with the longer ALD cycle times the structure might relax to the denser (lower V_{f.u}) structure with Pbca or Pnma structure. These observations highlight the complexity of the phase stabilization dynamics in ZrO₂ thin films deposited, suggesting a tunable control of the crystal structure via a proper choice of the ALD parameters, in addition to the deposition temperature.

Finally, we like to emphasize that the ALD process developed here possesses the following capabilities in a single process: (1) water-based chemistry, (2) wide and well-defined ALD windows, and (3) distinct temperature ranges yielding different ZrO₂ phases. These capabilities are critical for determining whether a process is suitable for real-world applications. Also importantly, the present ALD-grown o-ZrO₂ thin films were confirmed to be of high-quality, impurity-free, relatively smooth and air-stable, opening thus new opportunities for exploring and exploiting the unique properties of o-ZrO₂, such as the expected ferroelectricity, towards future electronic device applications.

CRedit authorship contribution statement

Basit Ali: Writing – original draft, Visualization, Investigation, Conceptualization. **Ramin Ghiyasi:** Writing – original draft, Validation, Methodology, Investigation, Conceptualization. **Joonas Pekkanen:** Writing – review & editing, Investigation. **Mika Lastusaari:** Writing – review & editing, Validation, Resources, Methodology. **Maarit Karppinen:** Writing – original draft, Validation, Supervision, Resources, Funding acquisition, Conceptualization.

Declaration of Competing Interest

The authors declare that they have no known competing financial interests or personal relationships that could have appeared to influence the work reported in this paper.

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Appendix A. Supporting information

Supplementary data associated with this article can be found in the online version at doi:10.1016/j.mtcomm.2026.115134.

Data Availability

Data will be made available on request.

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